

Ordering Guide

Sample Part Number: SKHC1-127-08-T100-SS-T0-F1-AIO

Chip Type	Solder Type	Sealant	Thickness Tolerance	Flatness Tolerance	Ceramic Type	Ceramic Surface
<i>SKHC1-127-08</i>						
SKHC1-127-08 127 couples, 8A max	T100 BiSn (up to 138C)	NS No Sealant	T0 ±0.1 mm	F0 ±0.05 mm	AIO Alumina (96% white)	- None
	T200 CuSn (up to 227C)	SS Silicone sealant	T1 ±0.05 mm	F1 ±0.025 mm	AlN Aluminum Nitride	M Metalized
		ES Epoxy Sealant	T2 ±0.025 mm	F2 ±0.0125 mm		
		CS Customer specified sealant				

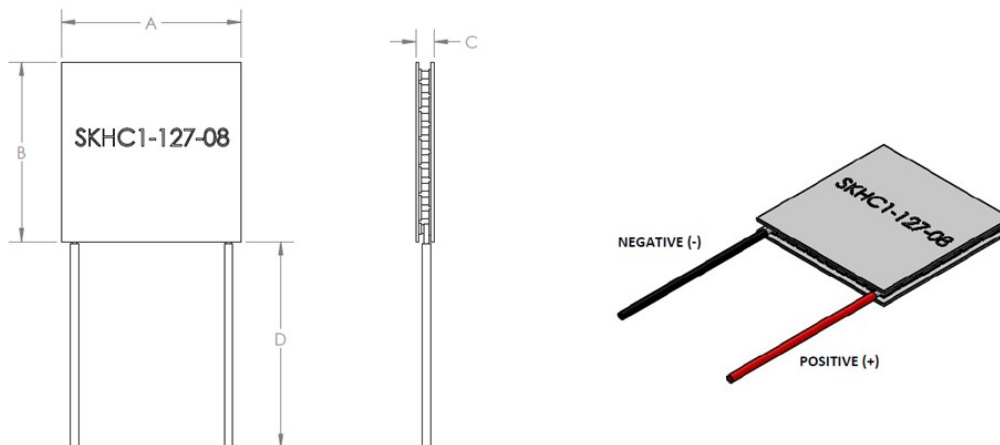
Performance Metrics

Cat Logic	Hot Side Temp T_h (°C)	ΔT_{max} (°C)	Q_{max} (Watts)	I_{max} (Amps)	V_{max} (DC Volts)	R_{AC} (Ω)	TE Dimensions (mm)			
							A	B	C	D
SKCH1-127-08	27	74	87	8.2	16.4	1.5	40	40	3.5	150
SKCH1-127-08	50	83	93.7	8.2	17.7	1.66	40	40	3.5	150

Notes:

All performance values fall within $\pm 10\%$ tolerance of tested data and/or models.
 Dimensions are typical and subject to change based on exact configuration ordered.
 Contact Sheetak at info@sheetak.com for additional performance data, chip options or customization

Chip Dimensions

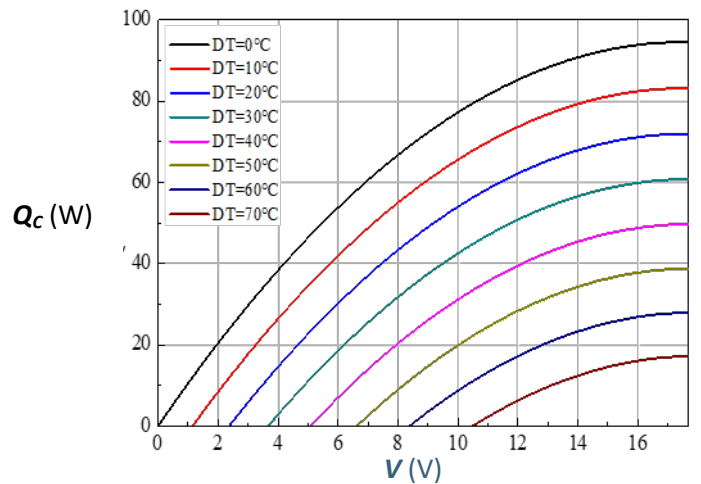
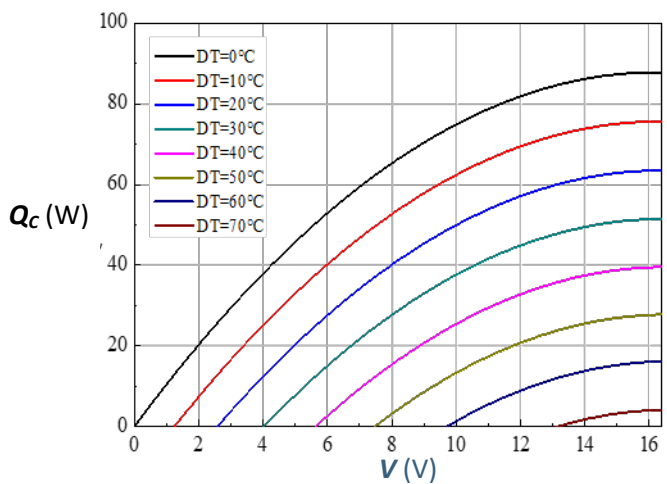
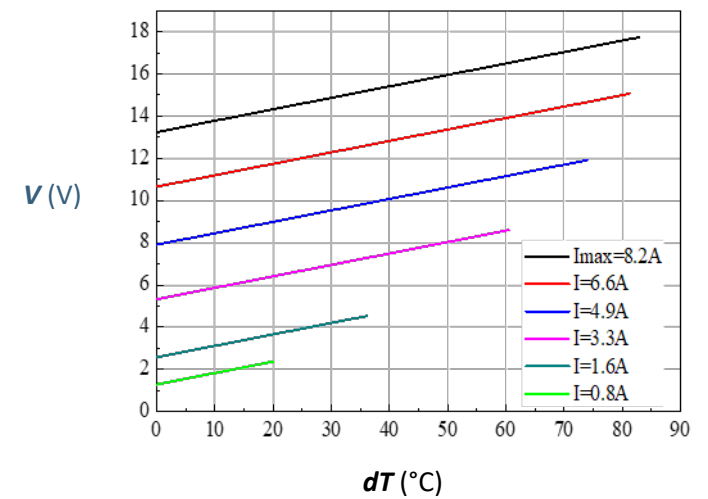
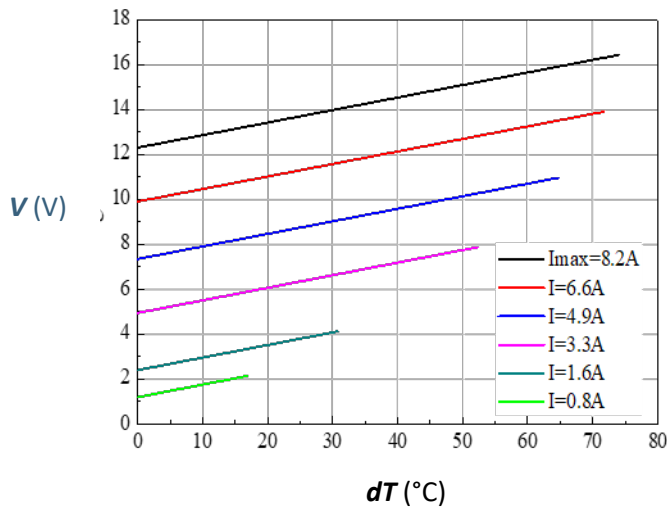
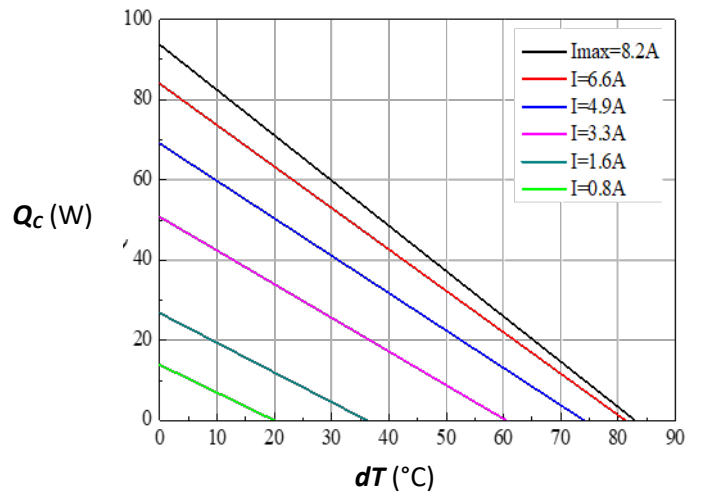
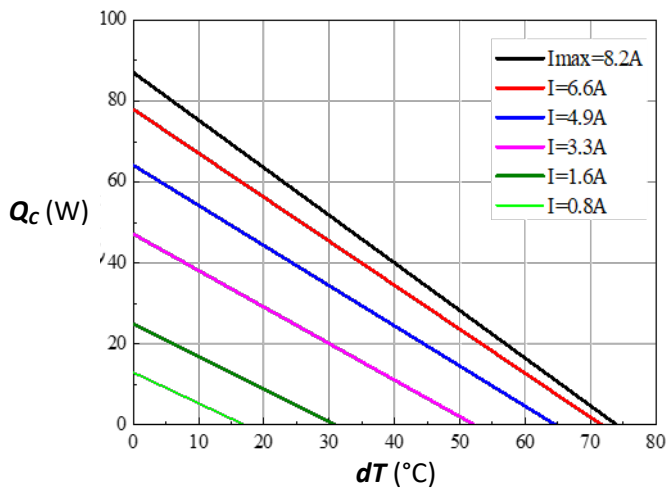


Notes:

Please see the *Ordering Guide* for flatness and thickness tolerances.
 Ceramic face with part number is the cold side and wires are soldered on the hot side.
 Some TECs may have a porch design or wires soldered on the side.

Performance Curves @ $T_H = 27^\circ\text{C}$

Performance Curves @ $T_H = 50^\circ\text{C}$



Performance Curves @ $T_H = 27^\circ\text{C}$

Performance Curves @ $T_H = 50^\circ\text{C}$

